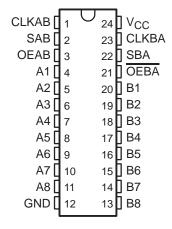
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at  $V_{CC}$  = 5 V,  $T_A$  = 25°C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

### description

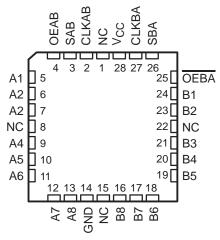
These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select either real-time or stored data for transfer. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT652A.

#### SN54ABT652A . . . JT OR W PACKAGE SN74ABT652A...DB, DW, NT, OR PW PACKAGE (TOP VIEW)



#### SN54ABT652A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

Data on the A- or B-data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control inputs. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last

To ensure the high-impedance state during power up or power down,  $\overline{\text{OEBA}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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## description (continued)

The SN54ABT652A is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT652A is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

#### **FUNCTION TABLE**

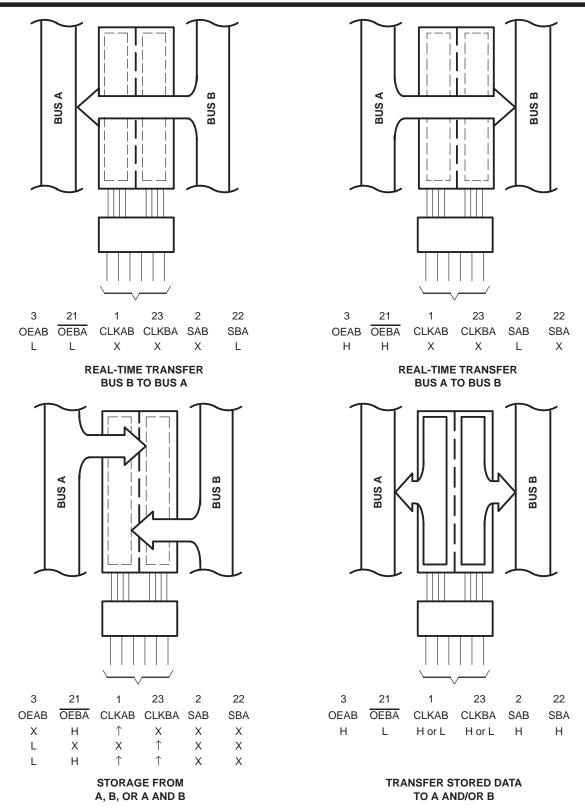
		INP	UTS			DATA	\ I/O†	ODERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	1	$\uparrow$	Χ	Χ	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Χ	Input	Unspecified <sup>‡</sup>	Store A, hold B
Н	Н	1	$\uparrow$	χ‡	Χ	Input	Output	Store A in both registers
L	Х	H or L	<b>↑</b>	Х	Χ	Unspecified <sup>‡</sup>	Input	Hold A, store B
L	L	$\uparrow$	$\uparrow$	X	X‡	Output	Input	Store B in both registers
L	L	Х	X	Х	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

<sup>†</sup> The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



<sup>‡</sup> Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered to load both registers.



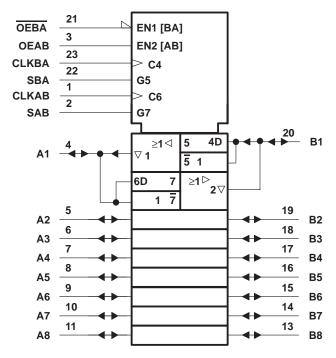
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

Figure 1. Bus-Management Functions



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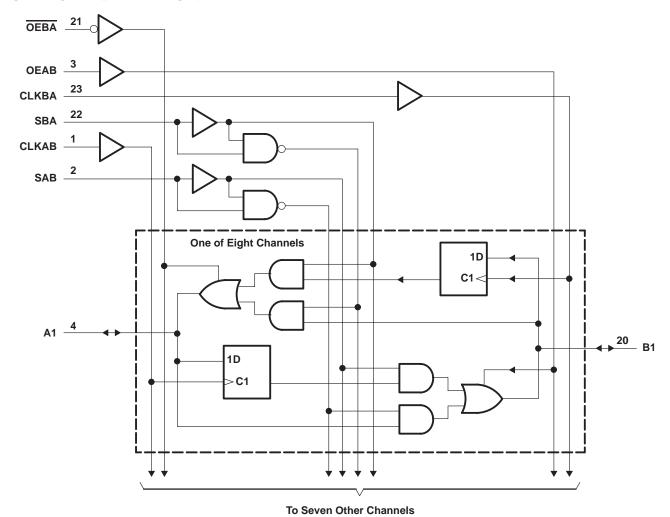
# logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



# logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see No		
Voltage range applied to any output in the high or	power-off state, V <sub>O</sub>	. −0.5 V to 5.5 V
Current into any output in the low state, Io: SN54	IABT652A	96 mA
SN74	4ABT652A	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D	DB package	104°C/W
D	DW package	81°C/W
N	IT package	67°C/W
Р	W package	120°C/W
Storage temperature range, T <sub>stg</sub>		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

## recommended operating conditions (see Note 3)

			SN54AB	T652A	SN74AB	T652A	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	Operating free-air temperature		<del>-</del> 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	DAMETER	TEST CO.	NDITIONS	Т	A = 25°C	;	SN54AB	T652A	SN74AB	T652A	UNIT
PAI	RAMETER	TEST CO	NDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ \/a		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
\/o\		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			٧
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	٧
V <sub>hys</sub>					100						mV
١.	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1		±1		±1	μА
tı	A or B ports	VCC = 5.5 V,	AL = ACC OL GIAD			±100		±100		±100	μΑ
lozh <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			50**		10		50	μΑ
loz <sub>L</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-50**		-10		-50	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
Io§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high			250		250		250	μΑ
Icc		$I_O = 0$ ,	Outputs low			30		30		30	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			250		250		250	μΑ
ΔICC¶		V <sub>CC</sub> = 5.5 V, One ir Other inputs at V <sub>CC</sub>				1.5		1.5		1.5	mA
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			7						pF
Cio	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			12						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>\*\*</sup> These limits apply only to the SN74ABT652A.

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup>The parameters IOZH and IOZL include the input leakage current.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $<sup>\</sup>P$  This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN54AE	3T652A		
		V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX			
fclock	Clock frequency	0	125	0	125	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	4		4		ns
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3.5		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	1.5		1.5	·	ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN74AE	MIN MAX  0 125 4		
		V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX			
fclock	Clock frequency	0	125	0	125	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	4		4		ns
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns



# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

				SN5	4ABT65	52A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
fmax			125	200		125		MHz
<sup>t</sup> PLH	CLK	B or A	2.2	4	5.1	1.7	5.9	ns
<sup>t</sup> PHL	OLK	DUIA	1.7	4	5.1	1.7	5.9	115
<sup>t</sup> PLH	A or B	B or A	1.5	3	4.8	1	5	ns
t <sub>PHL</sub>	AUID	BULA	1.5	3.3	4.6	1	5.6	115
t <sub>PLH</sub>	048 084	B or A	1.5	4	5.5	1.5	6.8	ns
t <sub>PHL</sub>	SAB or SBA†	BULA	1.5	3.6	4.9	1.5	6.2	110
<sup>t</sup> PZH	<del>OEBA</del>	А	2	3.6	5.4	2	6.8	ns
t <sub>PZL</sub>	OEBA	Α	3	5.7	7.7	3	9.2	115
t <sub>PHZ</sub>	OFDA.	А	1.5	3.2	5.8	1	7.5	ns
t <sub>PLZ</sub>	OEBA	۸	1.5	3	4.3	1	4.6	110
<sup>t</sup> PZH	OEAB	В	2	4.3	6.1	2	7.8	ns
t <sub>PZL</sub>	OEAB	Ь	3	5.5	7.4	3	8.9	110
t <sub>PHZ</sub>	OEAB	В		3.3	6	1	8	no
t <sub>PLZ</sub>	UEAD	D	1.5	3.4	5	1.5	6.8	→ ns

<sup>†</sup>These parameters are measured with the internal output state of the storage register opposite that of the bus input.

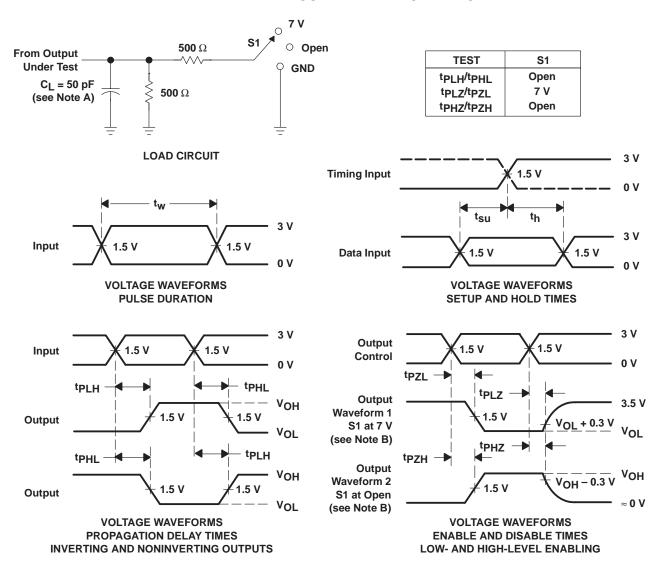
# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

				SN7	4ABT65	52A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
		(6611-61)		TYP	MAX			
f <sub>max</sub>			125	200		125		MHz
t <sub>PLH</sub>	CLK	B or A	2.2	4	5.1	2.2	5.6	ns
t <sub>PHL</sub>	OLK	BOIA	1.7	4	5.1	1.7	5.6	115
t <sub>PLH</sub>	A or B	B or A	1.5	3	4.3	1.5	4.8	ns
t <sub>PHL</sub>	AUID	BULA	1.5	3.3	4.6	1.5	5.4	110
t <sub>PLH</sub>	048 084	B or A	1.5	4	5.1	1.5	6.5	ns
t <sub>PHL</sub>	SAB or SBA†	D OI A	1.5	3.6	4.9	1.5	5.9	115
<sup>t</sup> PZH	<del>OEBA</del>	А	2	3.6	4.6	2	5.8	ns
t <sub>PZL</sub>	OEBA	^	3	5.7	6.8	3	8.5	110
<sup>t</sup> PHZ	OFDA	А	1.5	3.2	4.5	1.5	5	ns
t <sub>PLZ</sub>	OEBA	A	1.5	3	3.8	1.5	4.1	110
<sup>t</sup> PZH	OEAB	В	2	4.3	6.1	2	6.5	ns
t <sub>PZL</sub>	OEAB	Ь	3	5.5	6.5	3	7.4	115
<sup>t</sup> PHZ	OEAB	В	1.5	3.3	4.5	1.5	5.5	ns
t <sub>PLZ</sub>	OLAB		1.5	3.4	4.4	1.5	5.1	115

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O} = 50 \Omega$ ,  $t_{f} \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms





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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9324202Q3A	ACTIVE	LCCC	FK	28	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9324202Q3A SNJ54ABT 652AFK	Samples
SN74ABT652ADBR	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB652A	Samples
SN74ABT652ADW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT652A	Samples
SN74ABT652ADWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT652A	Samples
SNJ54ABT652AFK	ACTIVE	LCCC	FK	28	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9324202Q3A SNJ54ABT 652AFK	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

# **PACKAGE OPTION ADDENDUM**

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ABT652A, SN74ABT652A:

Catalog: SN74ABT652A

Military: SN54ABT652A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT652ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT652ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT652ADBR	SSOP	DB	24	2000	356.0	356.0	35.0
SN74ABT652ADWR	SOIC	DW	24	2000	350.0	350.0	43.0

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



## \*All dimensions are nominal

	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ı	SN74ABT652ADW	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

## **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



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